DECLARATION FOR UTILITY OR DESIGN PATENT APPLICATION (37 CFR 1.63)

As a below named inventor, I hereby declare that:					
My residence, post office address, and citizenship are as stated below next to my name.					
I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:					
Coating composition and low dielectric siliceous material produced by using same					
the specification of which [X] is attached hereto OR					
[] was filed on, United States Application Number or PCT International Application Number and was amended on (if applicable).					
I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment specifically referred to above. I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56.					
I hereby claim foreign priority benefits under 35 U.S.C. 119(a)-(d) or 365(b) of any foreign application(s) for patent or inventor's certificate, or 365(a) of any PCT International application which designated at least one county other than the United States of America, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate, or of any PCT International application having a filing date before that of the application on which priority is claimed.					
Country	Foreign Filing Date (MM/DD/YY)	Priority Claimed			
Japan	08/12/2003	[x] Yes [] No			
I hereby claim the benefit under 35 U.S.C. 119(e) of any United States provisional application(s) listed below.					
Filing Date (MM/DD/YY)	[] Additional provisional application numbers are listed on a supplemental priority data sheet attached hereto.				
I hereby claim the benefit under 35 U.S.C. 120 of any United States application(s), or 365(c) of any PCT International application designating the United States of America, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of 35 U.S.C. 112, I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.					
	dress, and citizenship are as set and sole inventor (if only on listed below) of the subject mand low dielectric silice and low dielectric silice and was amended on	dress, and citizenship are as stated below next to my name. It and sole inventor (if only one name is listed below) or an elisted below) of the subject matter which is claimed and for an elisted below) of the subject matter which is claimed and for an elisted below) of the subject matter which is claimed and for an elisted below dielectric siliceous material produced , United States Application Number or and was amended on (if applicable). iewed and understand the contents of the above identified samendment specifically referred to above. sclose information which is material to patentability as defined an elisted below and have also identified below, by checking the unitor's certificate, or of any PCT International application have riority is claimed. Foreign Filing Date (MM/DD/YY) Japan 08/12/2003 der 35 U.S.C. 119(e) of any United States provisional application below and, inscipality the United States of America, listed below and, inscipality the United States of America, listed below and, inscipality the United States of America, listed below and, inscipality the United States of America, listed below and, inscipality the United States of America, listed below and, inscipality the United States of America, listed below and, inscipality the United States of America, listed below and, inscipality the United States of America, listed below and, inscipality the United States of America, listed below and, inscipality the United States of America, listed below and, inscipality the United States of America, listed below and, inscipality the United States of America, listed below and, inscipality the United States of America, listed below and, inscipality the United States of America, listed below and, inscipality the United States of America, listed below and, inscipality the United States of America, listed below and, inscipality the United States of America, listed below and, inscipality the United States of America, listed below and below the effect of the america and the united States a			

U.S. Parent Application or PCT Parent Number	Parent Filing Date (MM/DD/YY)	Parent Patent Number (if applicable)
PCT/JP2004/011135	08/04/2004	

As a named inventor, I hereby appoint the following registered practioner(s), respectively and individually, as my attorneys and/or agents, with full power of substitution and revocation, to prosecute this application and to transact all business in the U.S. Patent and Trademark Office:

CUSTOMER NUMBER 26,289

Direct all correspondence to:	AZ ELECTRONIC MATERIALS USA CORP. Industrial Property Department 70 Meister Avenue
	Somerville, NJ 08876 Telephone: 908/429-3536 Facsimile: 908/429-3650

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. 1001 and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

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